Supplier Name: Amkor Technology Phils., Inc.
Company Address: 119 North Science Ave., Laguna Technopark Inc. LTAI, Sta. Rosa, Laguna
Responder Contact Name: Bernadette Alvarez
Responder Contact Phone: 850-7000-7622/3339
Responder Contact email: bsalvar@amkor.com
Responder Title: ESH Manager
Date of Response: 15 October 2008

Responder Signature:

Instructions

Suppliers must provide the identity and % weight of ALL substances of very high concern (SVHC) present in products supplied to Maxim. SVHCs are defined by REACH Article 57 and in accordance with Directive 67/548/EEC. The criteria is set out in REACH Annex XIII. For more information see http://ec.europa.eu/environment/chemicals/reach/reach_intro.htm .

The list of SVHC substances is only for the currently known candidate listing as of Oct 1 2008. Additional updates to this listing are expected and additional requests for data on those new substances as added will be sent.

Data is to supplied for each material type/formulation used in our products. Where multiple suppliers are used, worse case data (highest value) should be shown. Examples: Material Type = Mold Compound, Name/Formula = Sumitomo EME-G600. Material Type = Leadframe, Name/Formula = Cu alloy C194.

Where there is no content of the substance, enter 0%.
Insert additional rows as needed to reflect content of substances per material used.

		% Weight of Substance/CAS number																
		Anthracene (CAS No. 120-12-7)	4,4'-diaminodiphenylmethane (CAS No. 101-77-9)	Dibutyl phthalate (DBP) (CAS No. 84-74-2)	Cyclododecane (CAS No. 294-62-2)	Cobalt dichloride (CAS No. 7646-79-9)	Diarsenic pentaoxide (CAS No. 1303-28-2)	Diarsenic trioxide (CAS No. 1327-53-3)	Sodium dichromate, dihydrate (CAS No. 7789-12-0)	5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene) (CAS No. 81-15-2)	Bis (2-ethylhexyl)phthalate (DEHP) (CAS No. 117-81-7)	Hexabromocyclododecane (HBCDD) (CAS No. 25637-99-4)	Short chain chlorinated paraffins (SCCPs) (CAS No. 85535-84-8)	Bis(tributyltin)oxide (CAS No. 56-35-9)	Lead hydrogen arsenate (CAS No. 7784-40-9)	Triethyl arsenate (CAS No. 15606-95-8)	Benzyl butyl phthalate (BBP) (CAS No. 85-68-7)
Material Type	Laminate	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	JCI - HL832																
Material Type	Laminate	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	Samsung - HL832																
Material Type	Laminate	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	Kinsus - HL832																
Material Type	Laminate	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	K Circuit - HL832																
Material Type	Laminate	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	NanYa - HL832																
Material Type	Laminate	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	UMTC - HL832																
Material Type	Laminate	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	PPT - HL832																
Material Type	Mold Compound	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	Nitto GE-100L																
Material Type	Mold Compound	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	Cookson SMT-B1RC																
Material Type	Mold Compound	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	Sumitomo EME- 7730L																
Material Type	Wire	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	Heraeus - Au wire (HTS)																
Material Type	Wire	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	Heesung - Au wire (HTS)																
Material Type	Wire	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	Tanaka - Au wire (GL2)																
Material Type	Wire	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	Tanaka - Au wire (Alloy:Au/Pd)																
Material Type	Epoxy	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	Ablestik - Ablebond 2300																
Material Type	Epoxy	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	Ablestik - Ablebond 8360																
Material Type	Epoxy	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	Ablestik - Ablebond 8510AA																
Material Type	Solder Ball	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	Cookson - SN63/PB37																
Material Type	Solder Ball	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	Cookson - SN95.5/AG4.0/CU0.5																
Material Type	Solder Ball	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	MKE - SN63/PB37																
Material Type	Solder Ball	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	Mitsui - SN86.5/AG3.0/CU0.5																
Material Type	Tray	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%	0%
Material Name/Formula	EPAK MPPO Tray																
Material Type																	
Material Name/Formula																	